BC807 SERIES

SURFACE MOUNT SILICON PNP TRANSISTORS



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DESCRIPTION:

The CENTRAL SEMICONDUCTOR BC807 series devices are silicon PNP transistors, epoxy molded in a surface mount package, designed for general purpose switching and amplifier applications.

MARKING CODE: SEE MARKING CODE TABLE ON FOLLOWING PAGE



MAXIMUM F	RATINGS: (T _A =25°C)	SYMBOL			UNITS
Collector-Bas	se Voltage	V_{CBO}	5	0	V
Collector-Em	itter Voltage	V_{CEO}	4	5	V
Emitter-Base	Voltage	V_{EBO}	5	.0	V
Continuous (Collector Current	IC	50	00	mA
Power Dissip	pation	P_{D}	30	00	mW
Operating an	nd Storage Junction Temperature	T _J , T _{stg}	-65 to	+150	°C
Thermal Res	sistance	$\Theta_{\sf JA}$	4	17	°C/W
ELECTRICA	L CHARACTERISTICS: (T _A =25°C	unless otherwise r	noted)		
SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNITS
I _{CBO}	V _{CB} =20V			100	nA
ICBO	V_{CB} =20V, T_J =150°C			5.0	μΑ

SYMBOL I _{CBO}	TEST CONDITIONS V _{CB} =20V	MIN	TYP	MAX 100	UNITS nA
ICBO	V _{CB} =20V, T _J =150°C			5.0	μΑ
BVCES	I _C =10μA	50			V
BV_{CEO}	I _C =10mA	45			V
BVEBO	I _E =1.0μA	5.0			V
V _{CE} (SAT)	I _C =500mA, I _B =50mA			0.7	V
V _{BE(ON)}	V _{CE} =1.0V, I _C =500mA			1.2	V
f _T	V_{CE} =5.0V, I_{C} =10mA, f=100MHz	200			MHz
C_{ob}	V _{CB} =10V, f=1.0MHz		10		pF

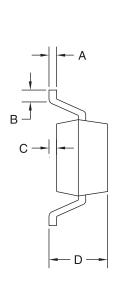
		BC807		BC8	807-16 BC8		807-25 BC8		<u> 307-40</u>	
		MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
hFE	V_{CE} =1.0V, I_{C} =100mA	100	600	100	250	160	400	250	600	
hFE	V _{CE} =1.0V, I _C =500mA	40	-	40	-	40	-	40	-	

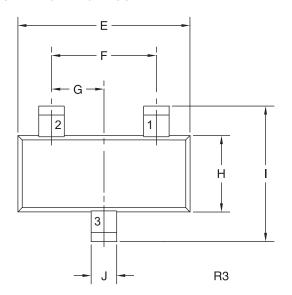
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SURFACE MOUNT SILICON PNP TRANSISTORS



SOT-23 CASE - MECHANICAL OUTLINE





LEAD CODE:

- 1) Base 2) Emitter 3) Collector

DEVICE	MARKING CODE
BC807	(any below)
BC807-16	5A or 5Ac
BC807-25	5B or 5Bc
BC807-40	5C or 5Cc

DIMENSIONS						
	INCHES		MILLIMETERS			
SYMBOL	MIN	MAX	MIN	MAX		
Α	0.003	0.007	0.08	0.18		
В	0.006	-	0.15	-		
С	-	0.005	-	0.13		
D	0.035	0.043	0.89	1.09		
Е	0.110	0.120	2.80	3.05		
F	0.075		1.90			
G	0.037		0.95			
Н	0.047	0.055	1.19	1.40		
	0.083	0.098	2.10	2.49		
J	0.014	0.020	0.35	0.50		

SOT-23 (REV: R3)

OUTSTANDING SUPPORT AND SUPERIOR SERVICES



PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- · Inventory bonding
- · Consolidated shipping options

- · Custom bar coding for shipments
- · Custom product packing

DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free guick ship samples (2nd day air)
- Online technical data and parametric search
- SPICE models
- · Custom electrical curves
- · Environmental regulation compliance
- · Customer specific screening
- · Up-screening capabilities

- · Special wafer diffusions
- PbSn plating options
- Package details
- Application notes
- · Application and design sample kits
- · Custom product and package development

REQUESTING PRODUCT PLATING

- 1. If requesting Tin/Lead plated devices, add the suffix "TIN/LEAD" to the part number when ordering (example: 2N2222A TIN/LEAD).
- 2. If requesting Lead (Pb) Free plated devices, add the suffix "PBFREE" to the part number when ordering (example: 2N2222A PBFREE).

CONTACT US

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